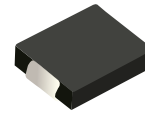
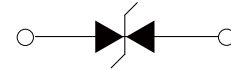


## FEATURES

- | Low profile package
- | Ideal for automated placement
- | 5000 Watt peak pulse power capability with a 10/1000 $\mu$ s waveform
- | For surface mounted applications to optimize board space
- | Excellent clamping capability
- | Very fast response time
- | Low incremental surge resistance
- | Meet AEC-Q101 Requirements



DO-214AB(SMC)



Schematic Symbol

## APPLICATIONS

- | Power supply protection
- | Automotive application
- | Industrial application
- | Power management

## APPROVALS

<b>RoHS</b>	Compliance with 2011/65/EU
<b>HF</b>	Compliance with IEC61249-2-21:2003

## MAXIMUM RATINGS ( $T_A=25^{\circ}\text{C}$ )

Parameter	Symbo	Value	Unit
Peak Pulse Power Dissipation on 10/1000 $\mu$ s waveform (Note1, Note2).	$P_{PPM}$	5000	Watts
Steady State Power Dissipation at $T_L=50^{\circ}\text{C}$ , Lead lengths.375"(9.5mm) ( Note2)	$P_D$	6.5	Watts

- Notes :** 1.Non-repetitive current pulse, $T_A=25^{\circ}\text{C}$ .  
 2.Mounted on 5.0mm\*5.0mm (0.03mm thick) Copper Pads to each terminal.

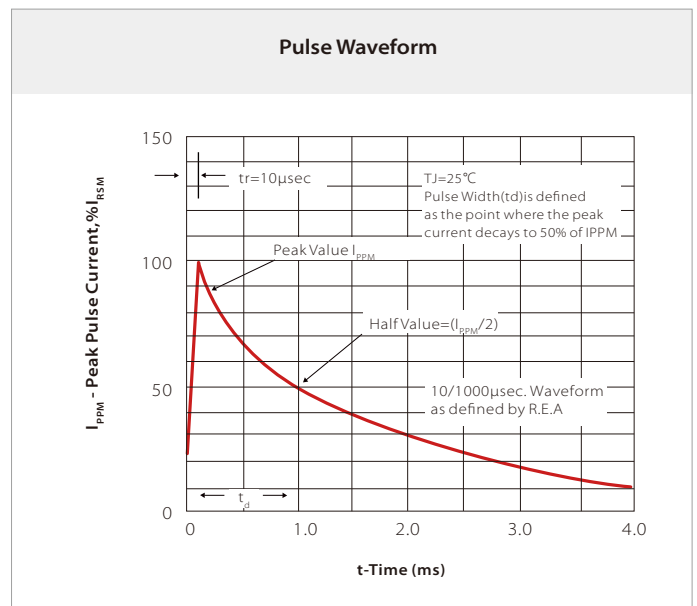
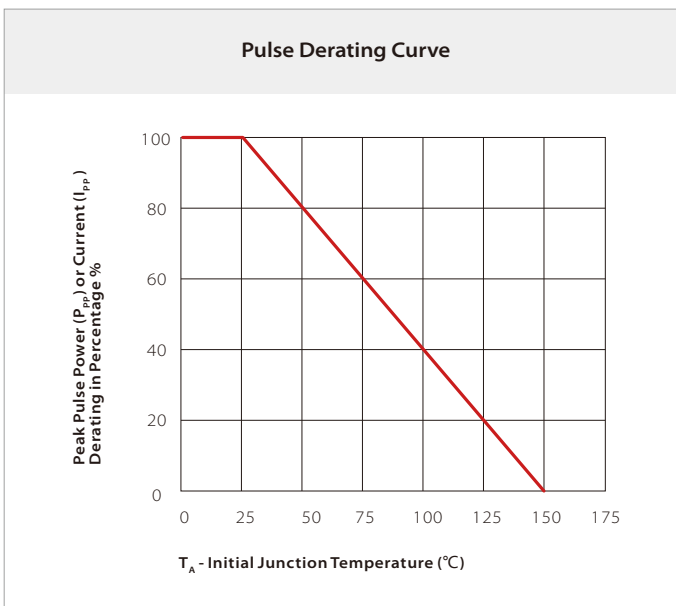
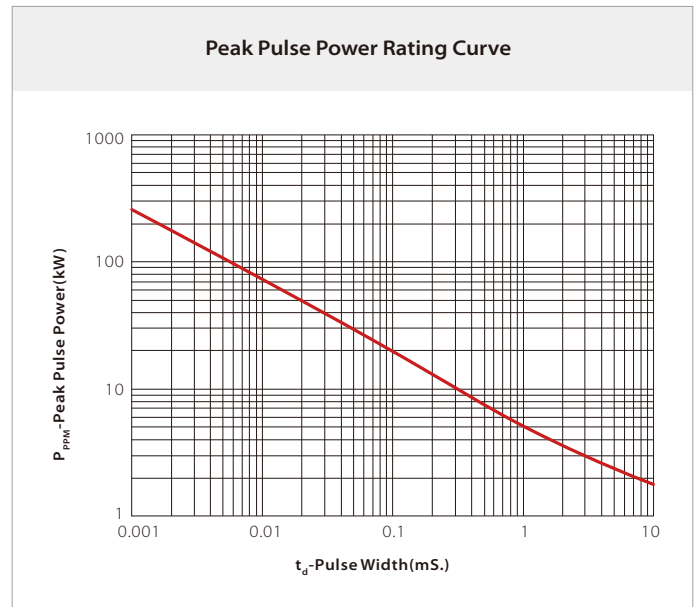
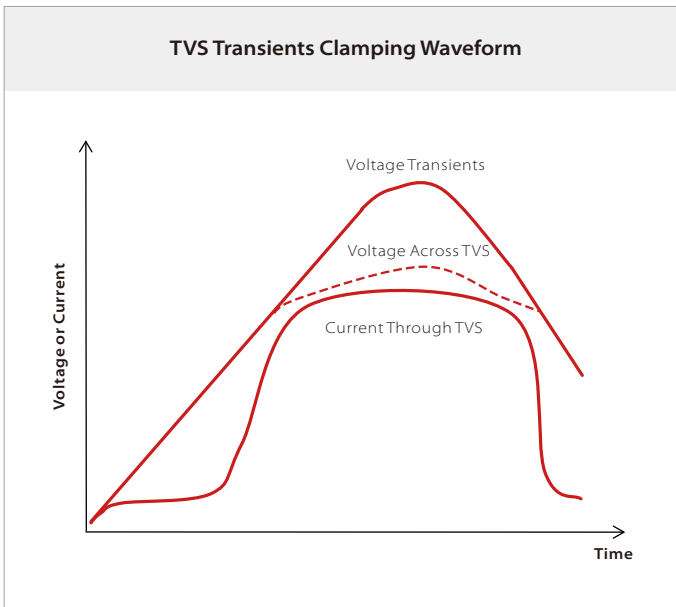
## THERMAL CONSIDERATIONS

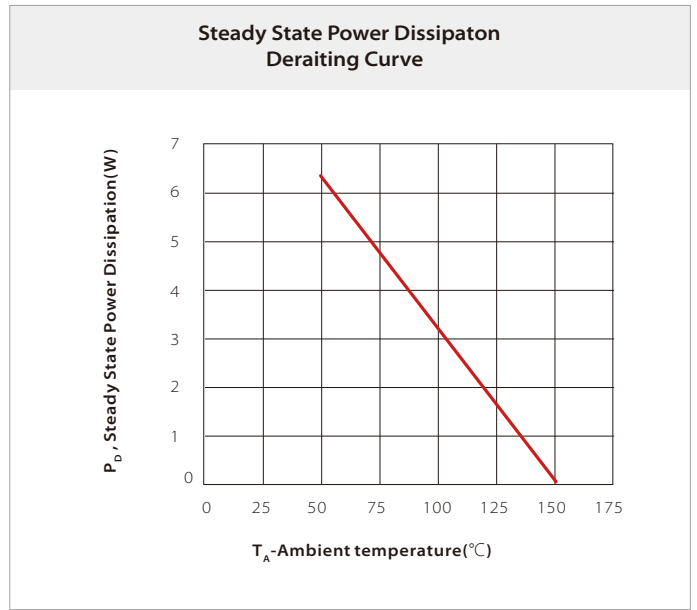
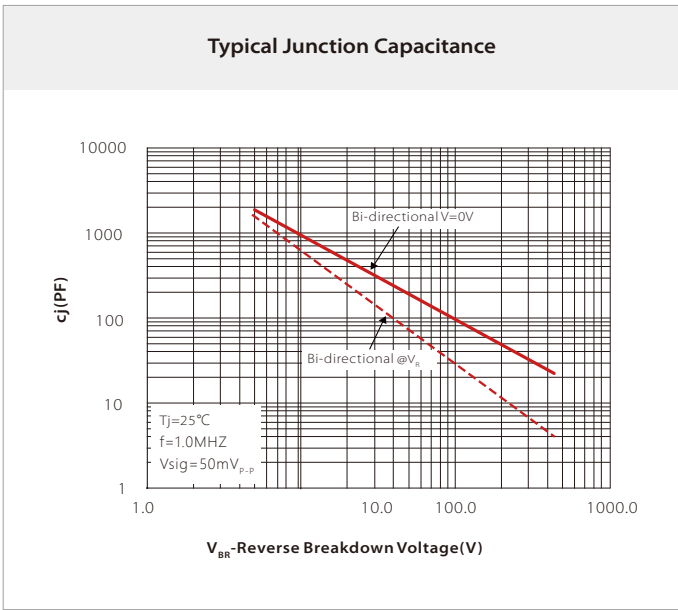
Parameter	Symbol	Value	Unit
Operating Junction Temperature	$T_J$	-55 to +150	$^{\circ}\text{C}$
Storage Temperature Range	$T_{STG}$	-55 to +150	$^{\circ}\text{C}$
Junction to Ambient on printed circuit	$R_{\theta JA}$	75	$^{\circ}\text{C}/\text{W}$

## ELECTRICAL CHARACTERISTICS (T<sub>A</sub>=25°C)

Part Number	Device Marking Code	Reverse Stand-off Voltage	Breakdown Voltage Min.@I <sub>T</sub>	Breakdown Voltage Max.@I <sub>T</sub>	Test Current	Maximum Clamping Voltage @I <sub>pp</sub>	Peak Pulse Current	Reverse Leakage @V <sub>RWM</sub>
		V <sub>RWM</sub> (V)	V <sub>BR</sub> (V)	V <sub>BR</sub> (V)	I <sub>T</sub> (mA)	V <sub>C</sub> (V)	I <sub>pp</sub> (A)	I <sub>R</sub> (uA)
TPSVC500B30	5DBM	30.0	33.3	36.8	1.0	48.4	103.0	1.0

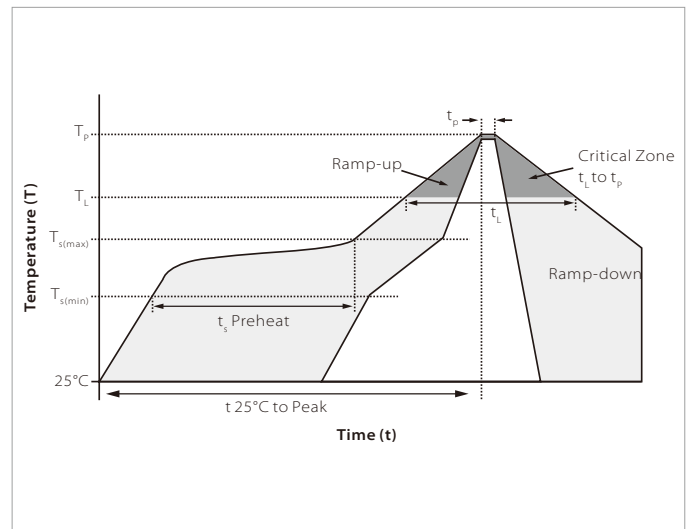
## CHARACTERISTIC CURVES



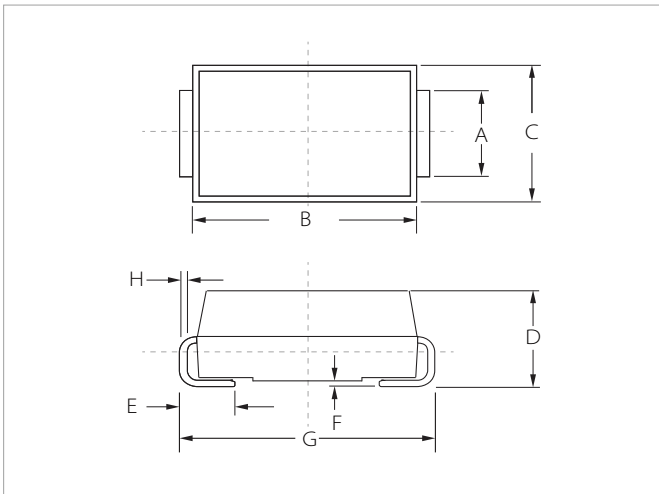


## SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ( $T_{s(min)}$ )	150 $^\circ\text{C}$
	Temperature Max ( $T_{s(max)}$ )	200 $^\circ\text{C}$
	Time (min to max) ( $t_2$ )	60 – 180 secs
Average ramp up rate (Liquidus Temp ( $T_L$ ) to peak)		3 $^\circ\text{C}/\text{second}$ max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3 $^\circ\text{C}/\text{second}$ max
Reflow	Temperature ( $T_L$ ) (Liquidus)	217 $^\circ\text{C}$
	Time (min to max) ( $t_1$ )	60 – 150 seconds
Peak Temperature ( $T_p$ )		260 $^\circ\text{C}$
Time within 5 $^\circ\text{C}$ of actual peak Temperature ( $t_p$ )		20 – 40 seconds
Ramp-down Rate		6 $^\circ\text{C}/\text{second}$ max
Time 25 $^\circ\text{C}$ to peak Temperature ( $T_p$ )		8 minutes max.
Do not exceed		260 $^\circ\text{C}$

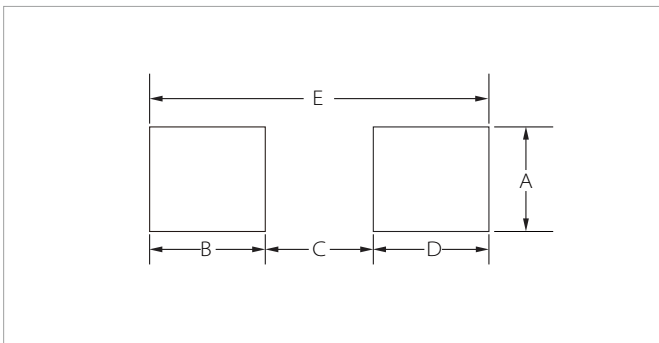


## DO-214AB(SMC) PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.80	3.20	0.110	0.126
B	6.60	7.20	0.260	0.283
C	5.70	6.10	0.224	0.240
D	2.15	2.75	0.085	0.108
E	1.00	1.60	0.039	0.063
F	0.02	0.20	0.000	0.008
G	7.60	8.00	0.299	0.315
H	0.15	0.30	0.006	0.012

## RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	3.30	-	0.129	-
B	2.40	-	0.094	-
C	-	4.20	-	0.165
D	2.40	-	0.094	-
E	8.20REF		0.323REF	

## ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
TPSVC500B30	DO-214AB(SMC)	3000PCS	13"

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